

Amendments to the Claims:

The following listing will replace all prior listing of claims in the application.

Listing of Claims:

CLAIMS

1. (Currently amended) ~~Lithography~~ A lithographic method involving
comprising the pressing of a substrate, including the method comprising:

a preparation step during which the a substrate surface (4) is covered with a layer;_i

a pressing step in which a mold comprising a pattern of recesses and protrusions is pressed so as to penetrate part a portion of the thickness of the aforementioned layer;_i

at least one ~~attacking~~ etching step in which the layer is ~~attacked~~ etched until parts of the surface of the substrate have been ~~stripped~~ exposed_i; and an

a substrate etching step, whereby wherein the substrate is etched using an etching pattern which is defined by the mold pattern, ~~which method is characterized in that~~

wherein the preparation step further comprises ~~a sub-step consisting of the formation of a lower~~ forming an internal sub-layer (2A) of curable material; ~~a step involving the and curing of said the internal~~ sub-layer, and ~~a sub-step consisting of the formation of~~ forming an outer external sub-layer (2B) which is adjacent to the cured internal sub-layer, and

wherein the pressing step ~~including penetration of the above-mentioned~~ further comprises penetrating the protrusions of the mold into ~~this external~~ the external sub-layer until it comes into the protrusions contact with this cured the internal sub-layer.

2. (Currently amended) ~~Method~~ The method according to claim 1, ~~characterized in that this lower~~ wherein the internal sub-layer is formed in contact with

the substrate surface of the ~~substrate~~ and in that wherein, during the attacking at least one etching step, the ~~lower~~ internal sub-layer is removed excavated through in the recesses of the external sub-layer and, during the substrate etching step, the substrate is attacked etched through the same recesses.

3. (Currently amended) ~~Method~~ The method according to claim 1 ~~or claim 2~~, characterized in that wherein the ~~lower~~ internal sub-layer and the external sub-layer are ~~made of~~ comprise the same material.

4. (Currently amended) ~~Method~~ The method according to ~~any one of claims~~ claim 1 to 3, characterized in that the wherein curing treatment includes the internal sub-layer comprises a heat treatment of the ~~lower~~ internal sub-layer at a temperature higher than its curing temperature, and wherein the pressing step is carried out at a pressing temperature higher than the a glass transition temperature of the external sub-layer.

5. (Currently amended) ~~Method~~ The method according to ~~any one of claims~~ claim 1 to 4, characterized in that wherein the curable material is comprises a polymer.

6. (Currently amended) ~~Method~~ The method according to ~~any one of claims~~ claim 1 to 5, characterized in that wherein the curable material is comprises a resin that ~~can~~ is formulated to be cross-linked.

7. (Currently amended) ~~Method~~ The method according to claim 5 ~~or 6~~, characterized in that wherein the curable material is comprises one of a negative resin or a positive resin.

8. (Currently amended) ~~Method~~ The method according to ~~any one of claims~~ claim 1 to 7, characterized in that wherein the ~~lower~~ internal sub-layer has a thickness ~~from~~ of 0.01 micron to 1 micron.

9. (Currently amended) ~~Method~~ The method according to ~~any one of claims~~ claim 1 to 8, characterized in that wherein the thickness of the external sub-layer is less than the depth of the pattern recesses of the ~~pattern of the mold~~.

10. (New) The method according to claim 6, wherein the curable material comprises one of a negative resin or a positive resin.